

# GESI EXPANSION BOARD

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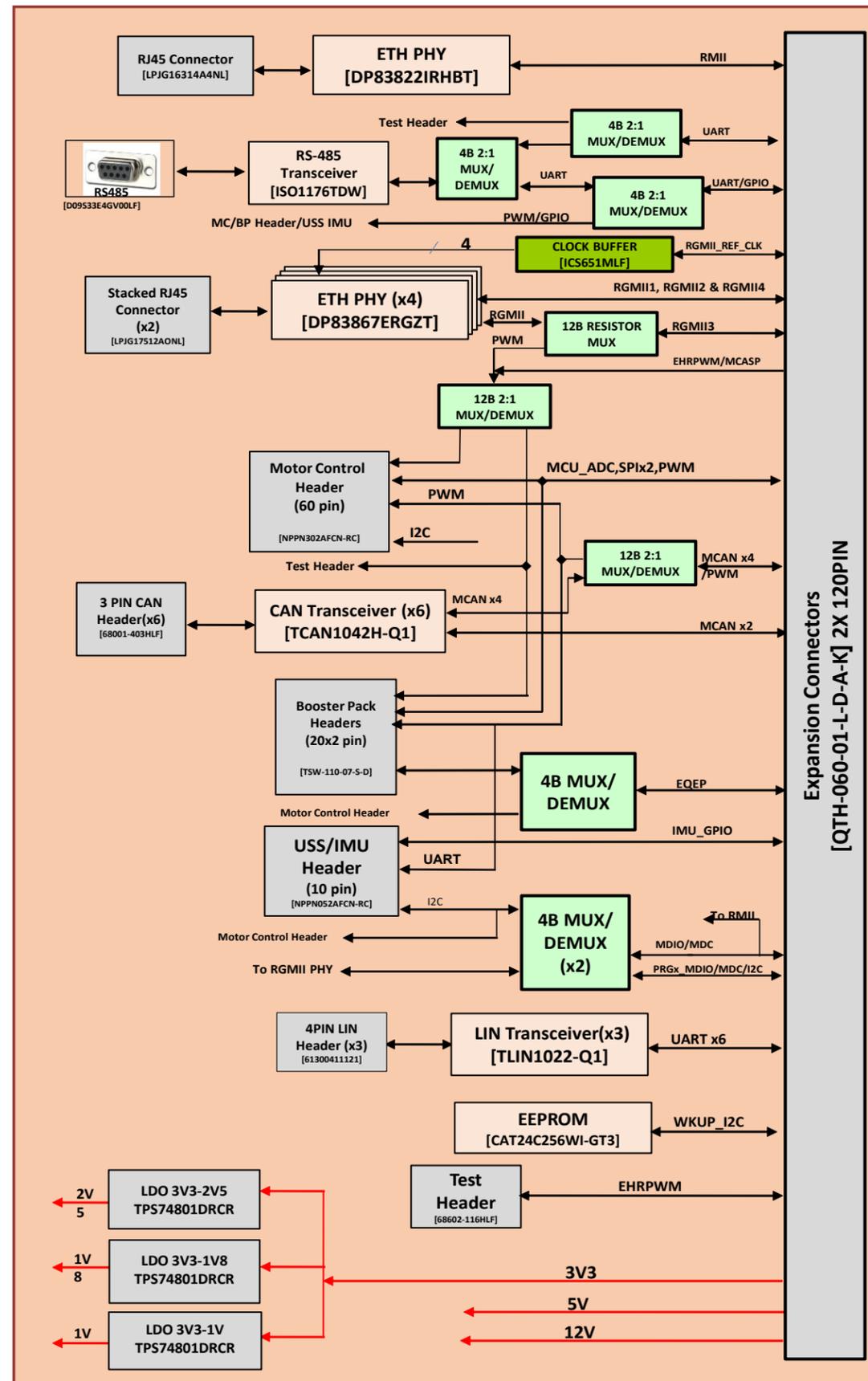
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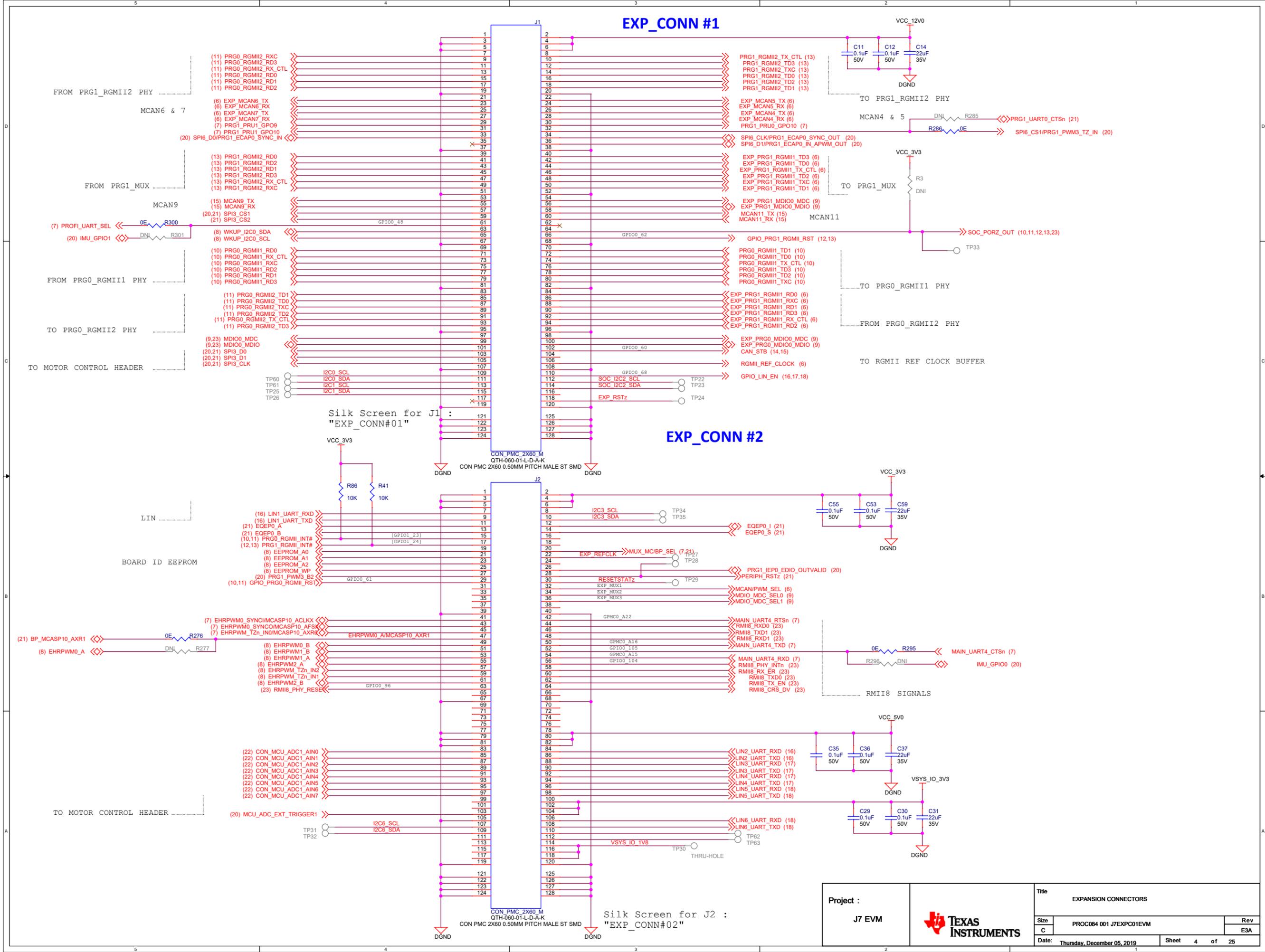
<b>REV</b>	E3A
<b>VER</b>	0.2

# REVISION HISTORY

VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
0.1	21-NOV-2019	Drafted from "PROC084E3_SCH, VER: 1.3". TP62 & TP63 moved to DNI and Hardware Schematic page Updated	Mistral Design Team		
0.2	26-NOV-2019	Updated the RGMII REF CLOCK Buffer U31 Part# to 651SDCGI	Mistral Design Team		

# BLOCK DIAGRAM



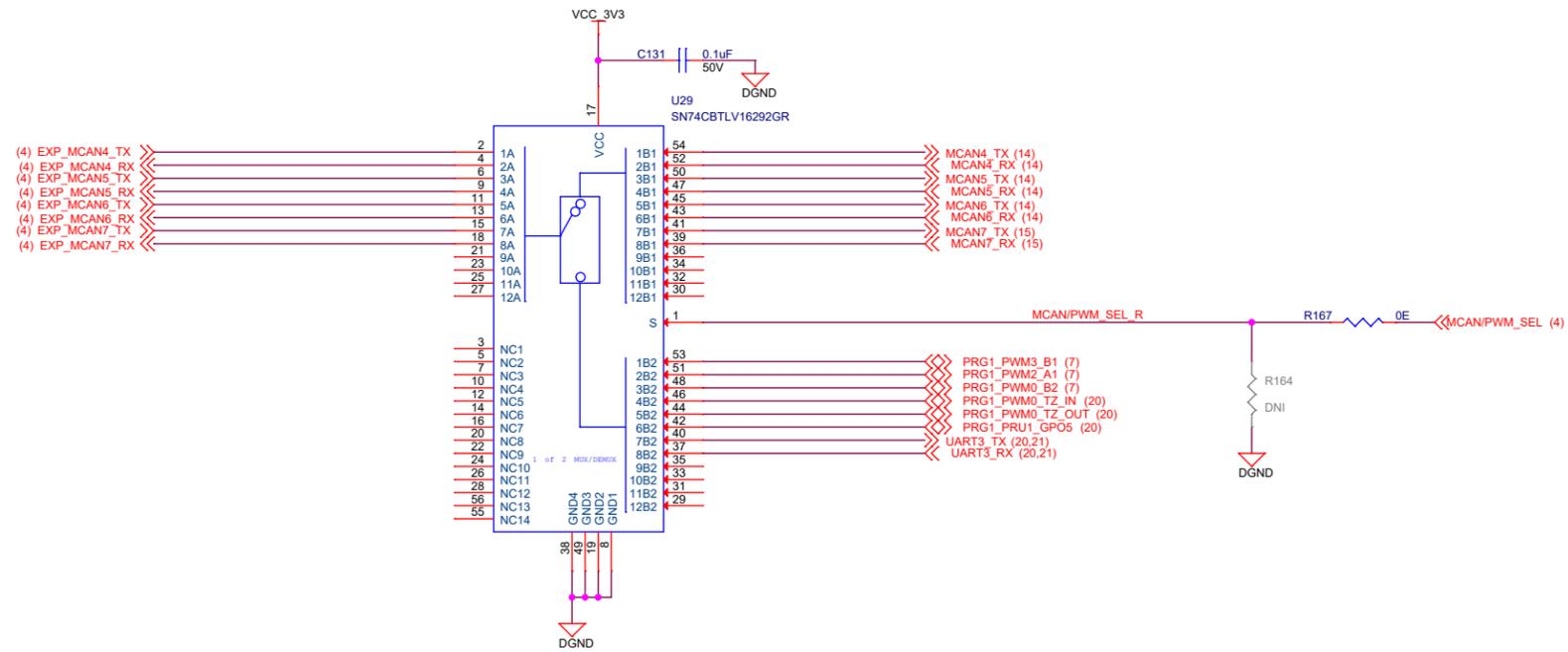
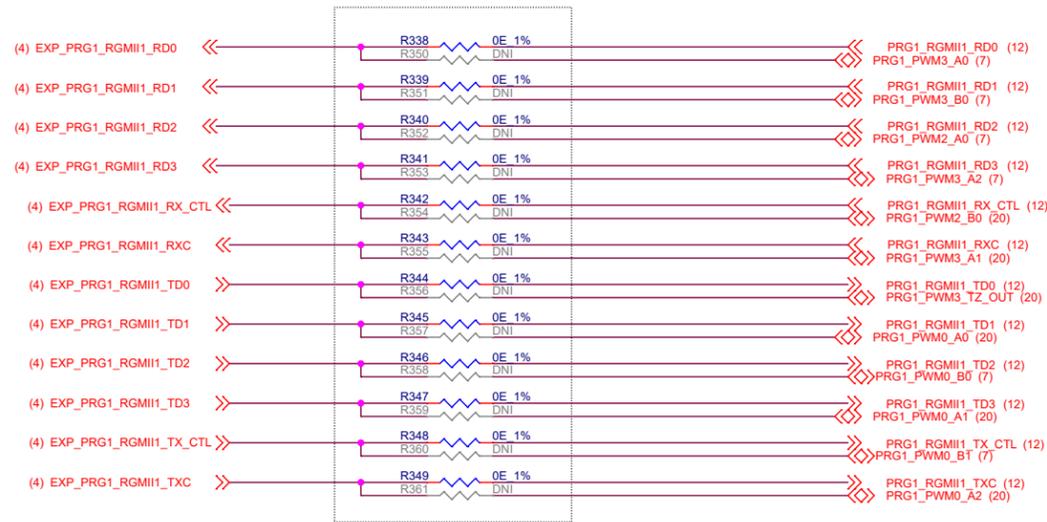


Project : <b>J7 EVM</b>		Title <b>EXPANSION CONNECTORS</b>	
		Size <b>PROC084 001 J7EXPC01EVM</b>	Rev <b>E3A</b>
		Date: <b>Thursday, December 05, 2019</b>	Sheet <b>4</b> of <b>25</b>

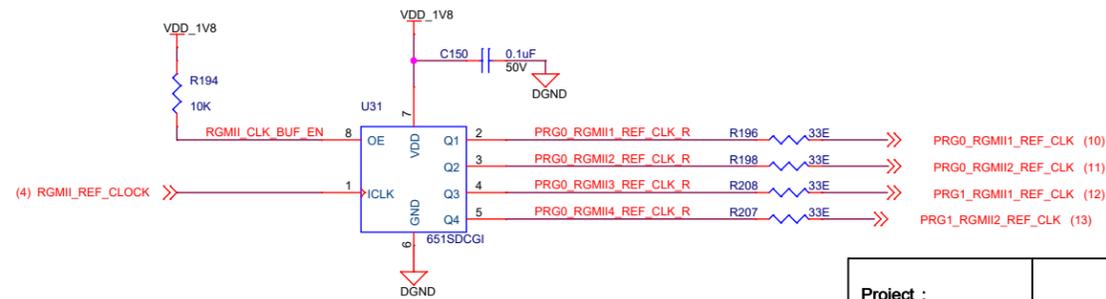
# PRG1 MUX - 01



PCB NOTE: keep these resistors placement as Tripad without stub in PCB

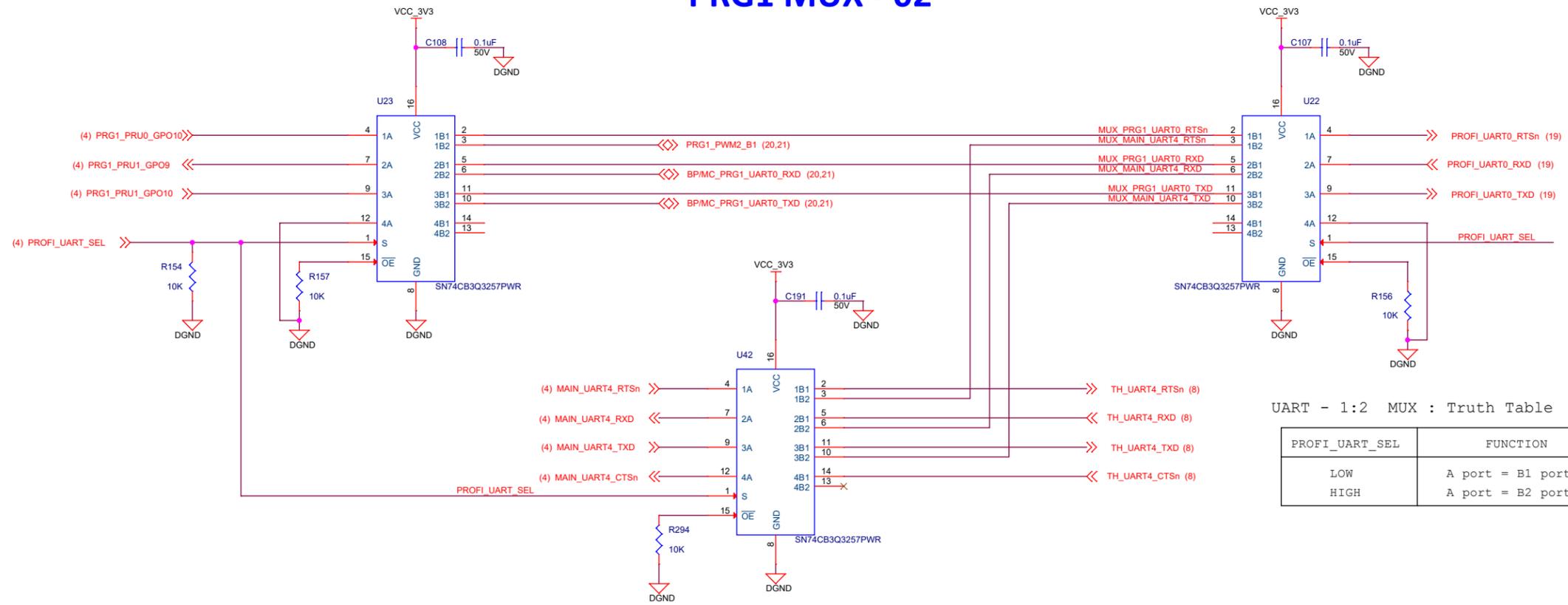


# RGMII REF CLOCK BUFFER



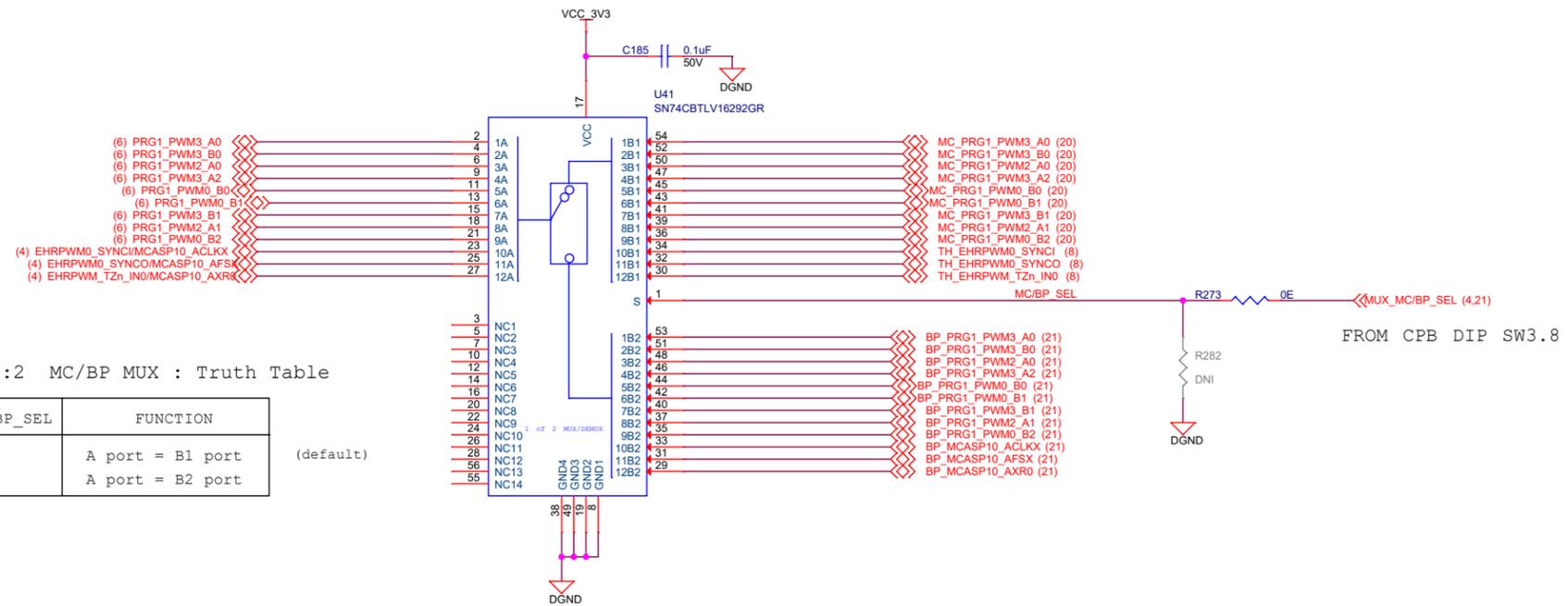
Project : J7 EVM		Title : PRG1 MUX - 01	
		Size : PROC084 001 J7EXPC01EVM	Rev : E3A
		Date : Thursday, December 05, 2019	Sheet 6 of 25

# PRG1 MUX - 02



UART - 1:2 MUX : Truth Table

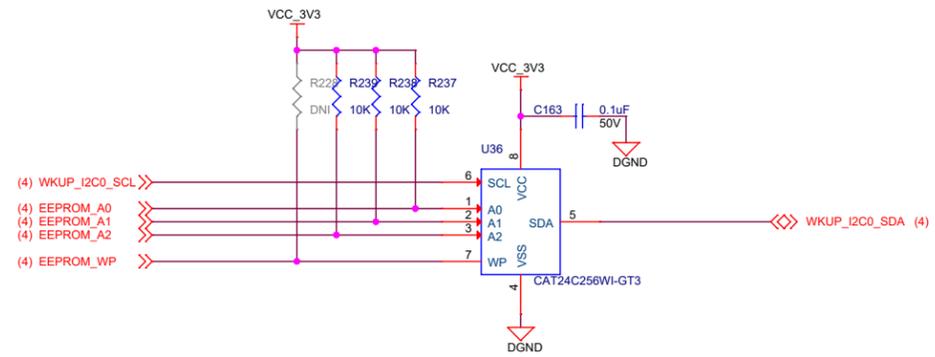
PROFI_UART_SEL	FUNCTION
LOW	A port = B1 port (default)
HIGH	A port = B2 port



PRG1 - 1:2 MC/BP MUX : Truth Table

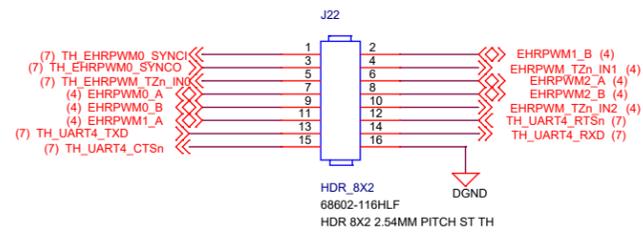
PRG1_MC/BP_SEL	FUNCTION
LOW	A port = B1 port (default)
HIGH	A port = B2 port

## BOARD ID EEPROM

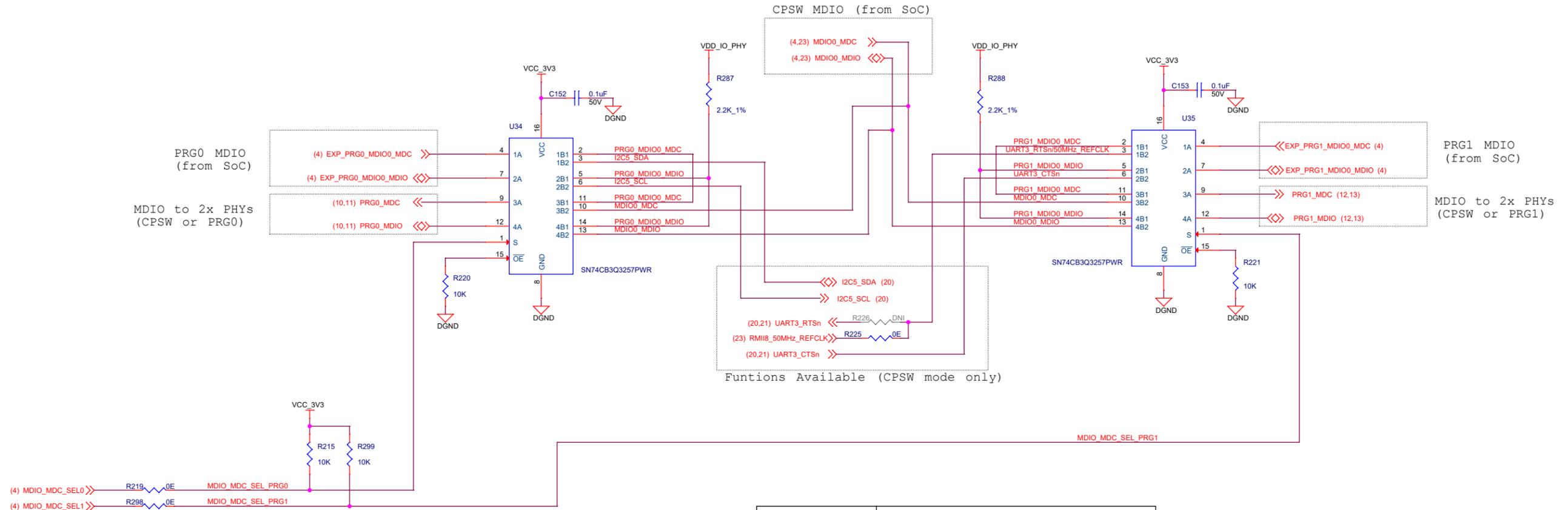


Note: EEPROM Address is 0x52 (set by base board)

## Test Connector



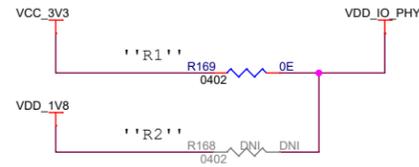
# MDIO MDC MUX



Functions Available (CPSW mode only)

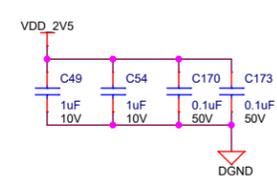
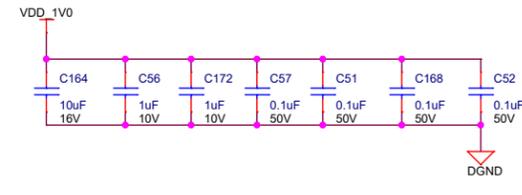
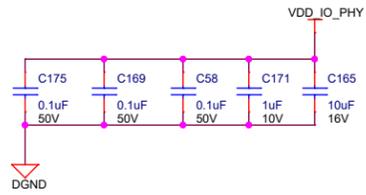
MDIO_MDC_SEL	MDIO/MDC PORT CONNECTION TO PHY's
LOW	PRGx MDIO/MDC
HIGH	CPSW9G MDIO/MDC

# IO Selection between 1.8V and 3.3V



IO Voltage for PHY Chips	Resistor Selection
3V3	Mount-R1 & DNI-R2
1V8	Mount-R2 & DNI-R1

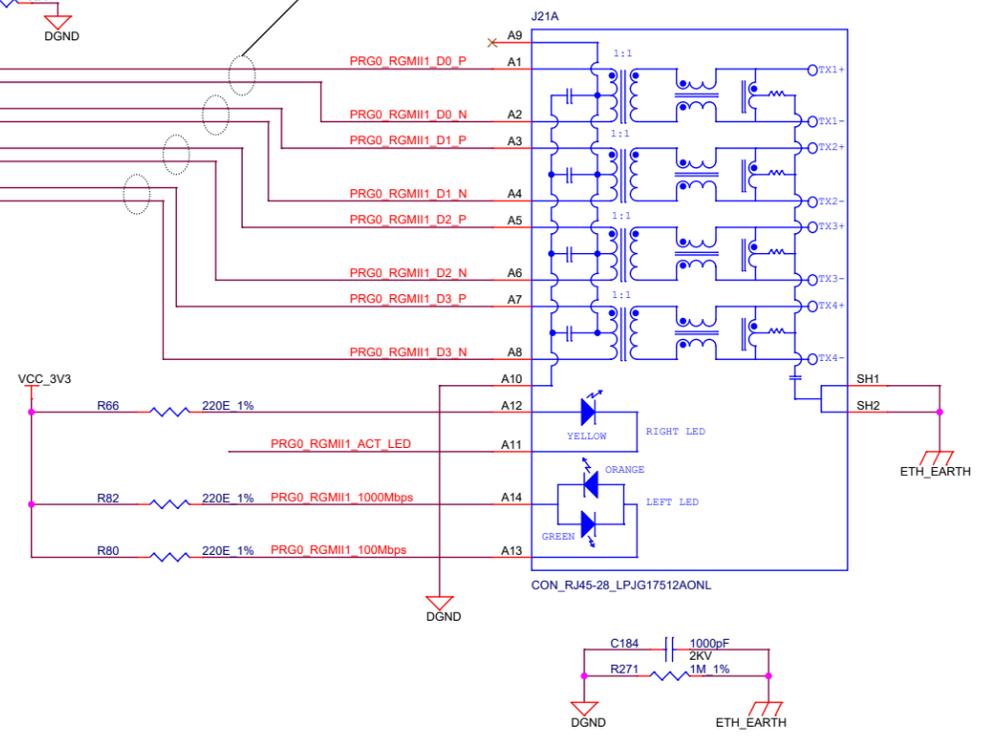
# PRG0\_GB\_ETHERNET RGMII 1



Silk Screen for J21 BOTTOM : "PRG0\_RGMII1"

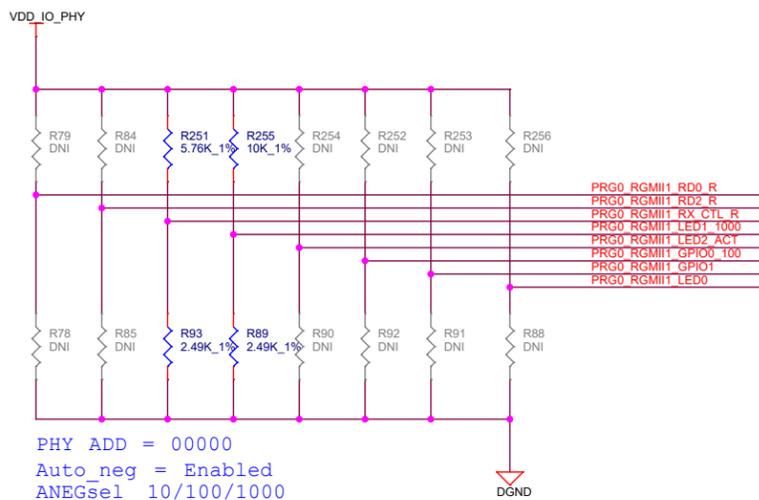
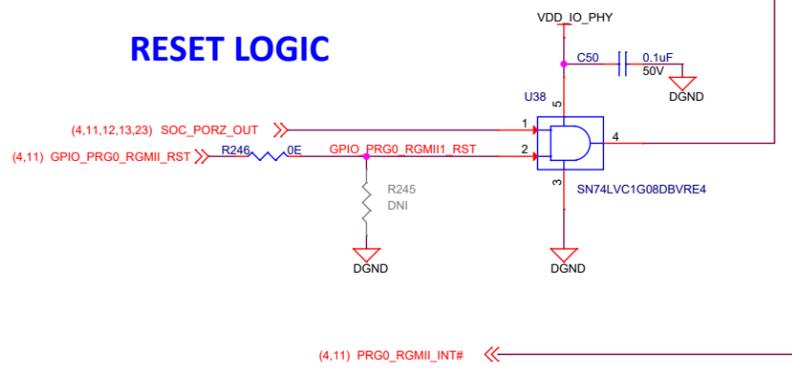
PCB Note: Route signals as 100-ohm differential

## RJ45



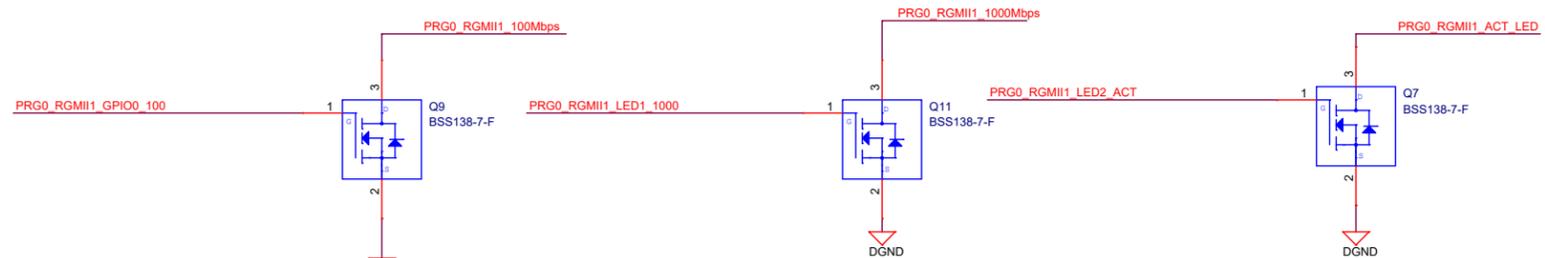
RJ45-LED	FUNCTION
YELLOW	ACTIVITY
ORANGE	1000Mbps Speed
GREEN	100Mbps Speed

## RESET LOGIC



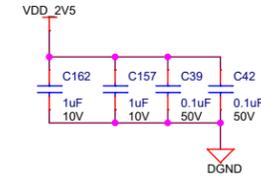
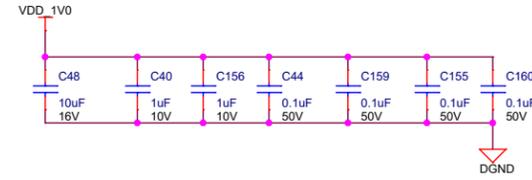
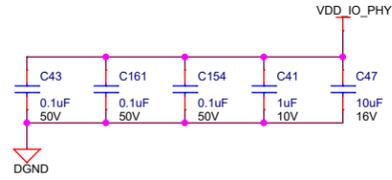
PHY ADD = 00000  
 Auto\_neg = Enabled  
 ANEGsel 10/100/1000  
 RGMII Clock Skew TX = 0ns  
 RGMII Clock Skew RX = 2ns

## SPEED AND ACTIVITY LED DRIVERS



# PRG0\_GB\_ETHERNET RGMII 2

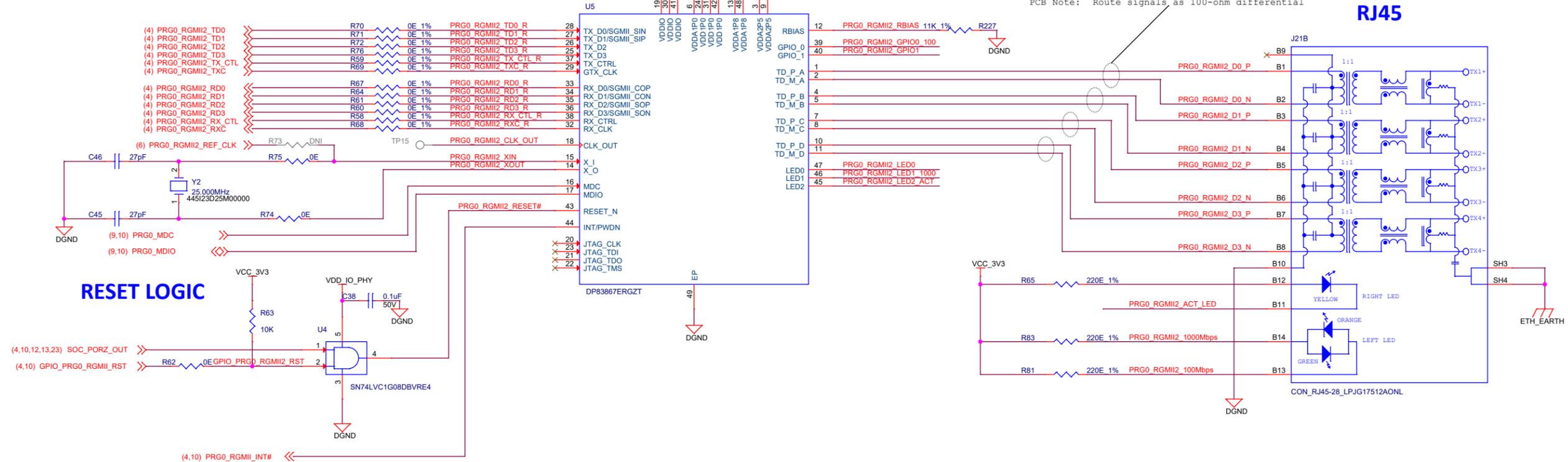
- TP48 PRG0\_RGMII2\_TD0
- TP49 PRG0\_RGMII2\_TD1
- TP50 PRG0\_RGMII2\_TD2
- TP51 PRG0\_RGMII2\_TD3
- TP52 PRG0\_RGMII2\_TX\_CTL
- TP53 PRG0\_RGMII2\_TXC
- TP54 PRG0\_RGMII2\_RD0
- TP55 PRG0\_RGMII2\_RD1
- TP56 PRG0\_RGMII2\_RD2
- TP57 PRG0\_RGMII2\_RD3
- TP58 PRG0\_RGMII2\_RX\_CTL
- TP59 PRG0\_RGMII2\_RXC



Silk Screen for J21 TOP :  
"PRG0\_RGMII2"

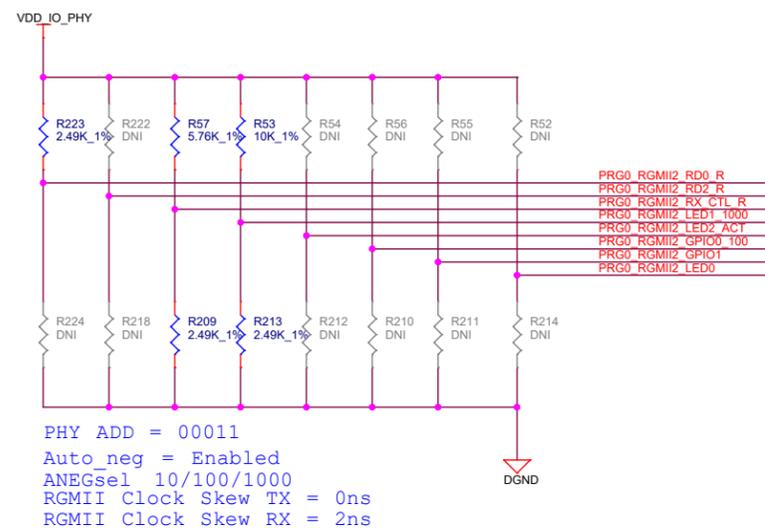
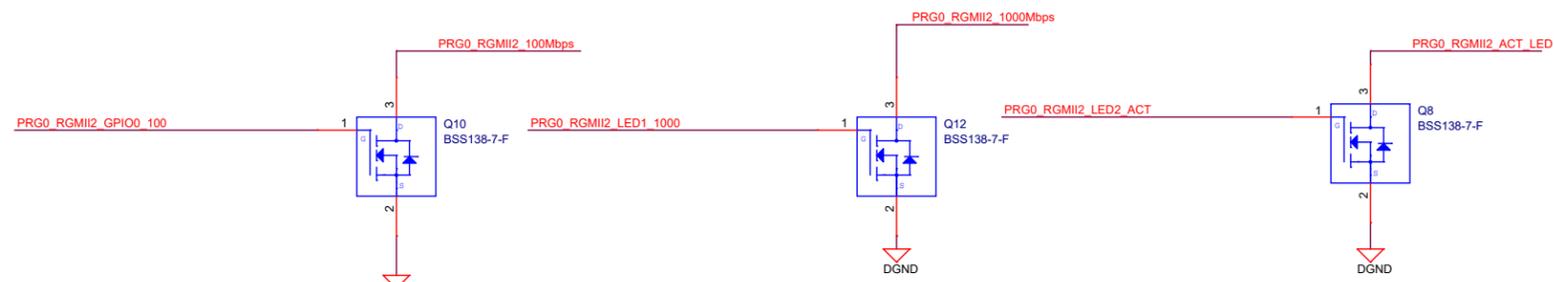
PCB Note: Route signals as 100-ohm differential

## RJ45

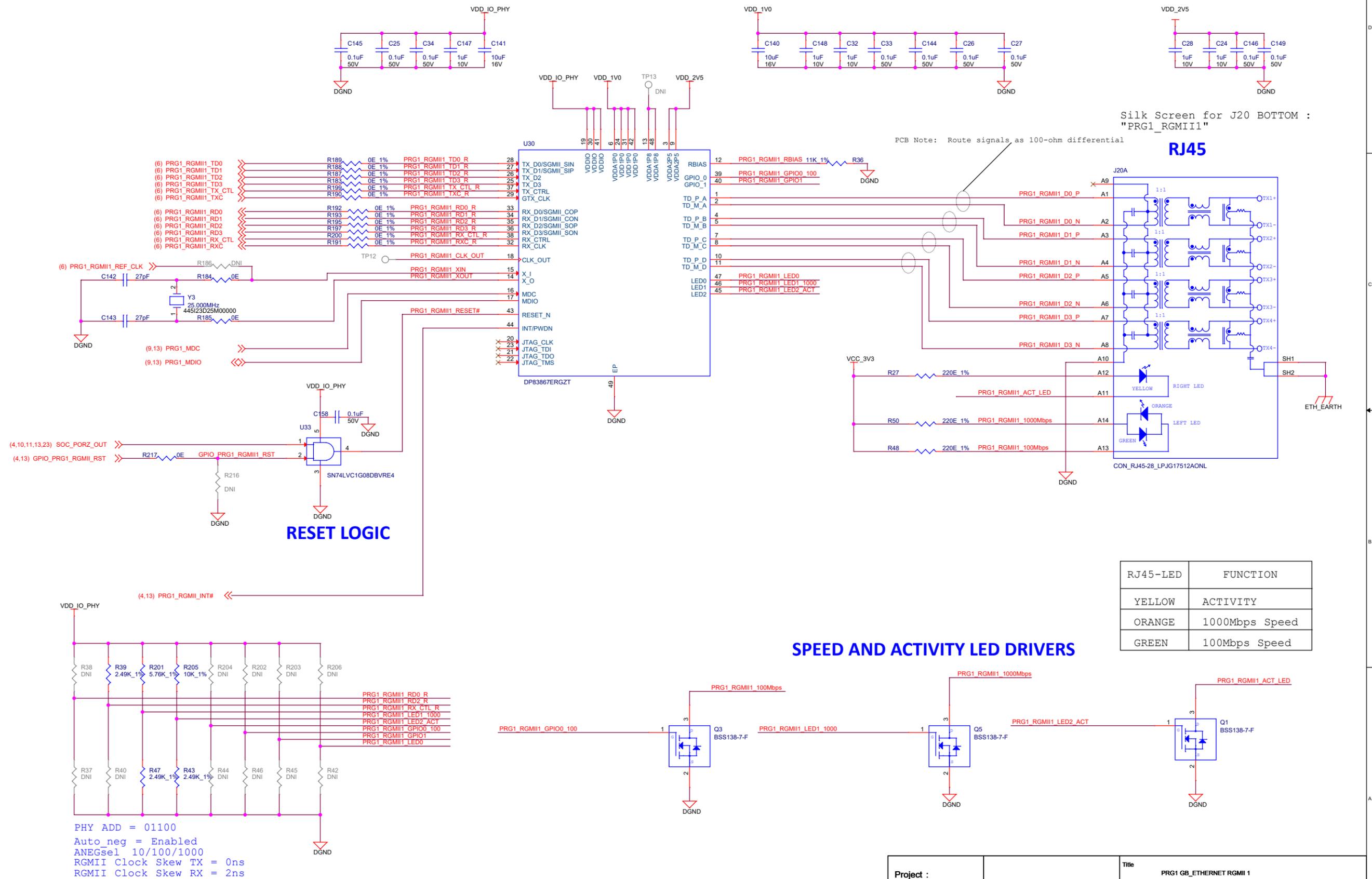


RJ45-LED	FUNCTION
YELLOW	ACTIVITY
ORANGE	1000Mbps Speed
GREEN	100Mbps Speed

## SPEED AND ACTIVITY LED DRIVERS



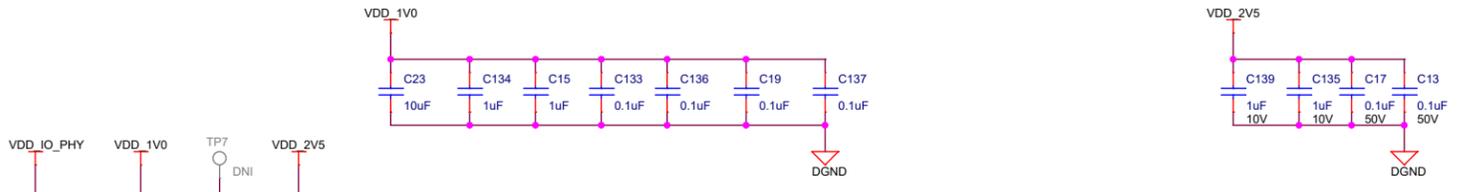
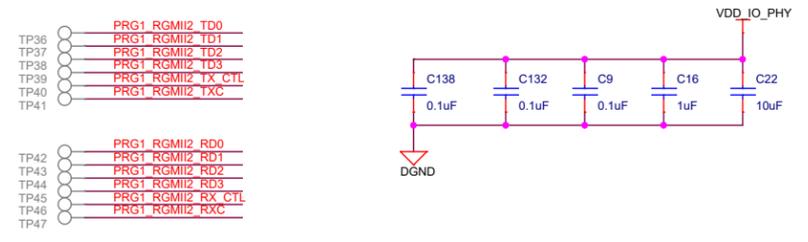
# PRG1 GB\_ETHERNET RGMII 1



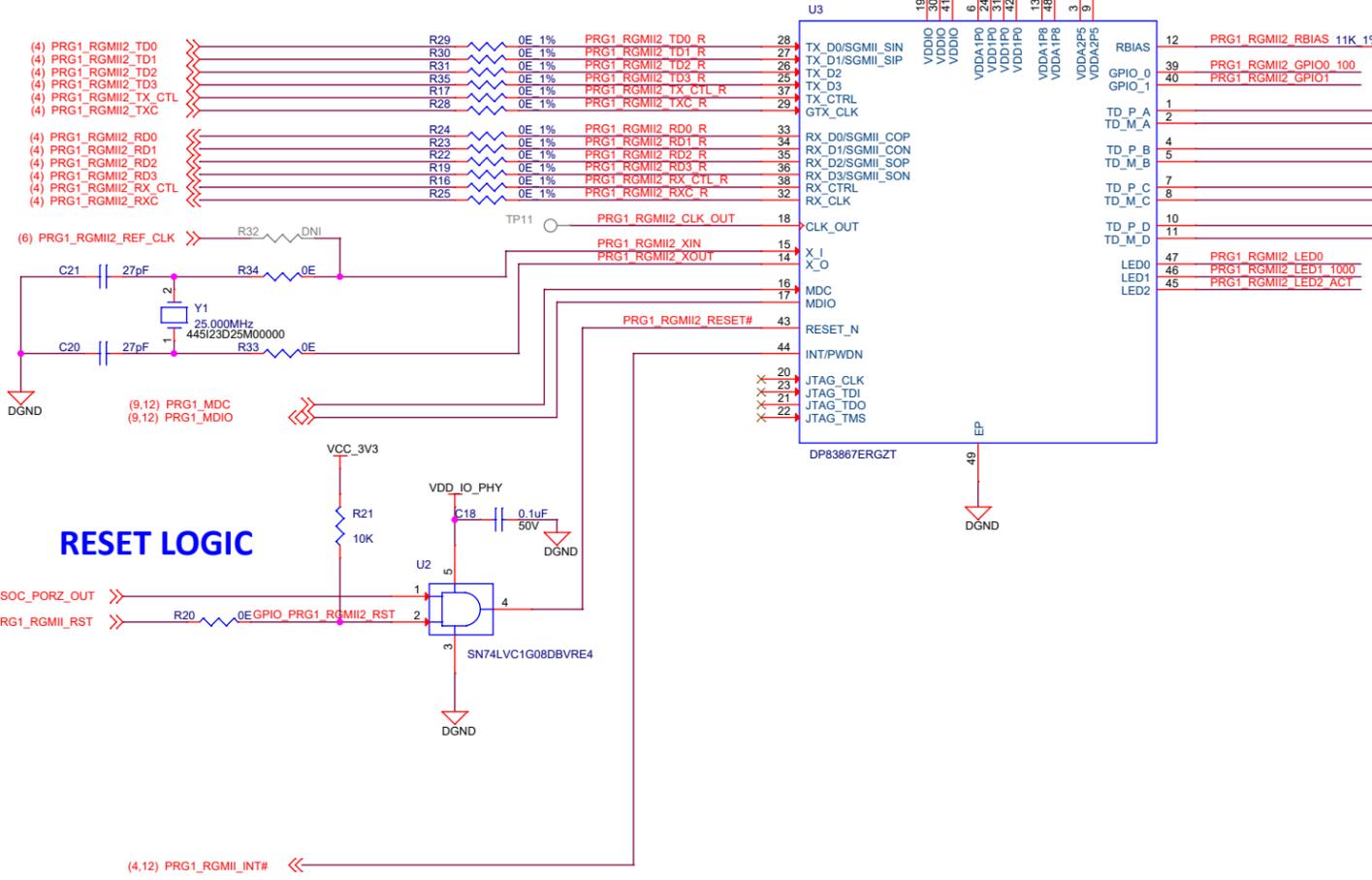
RJ45-LED	FUNCTION
YELLOW	ACTIVITY
ORANGE	1000Mbps Speed
GREEN	100Mbps Speed

## SPEED AND ACTIVITY LED DRIVERS

# PRG1\_GB\_ETHERNET RGMII 2

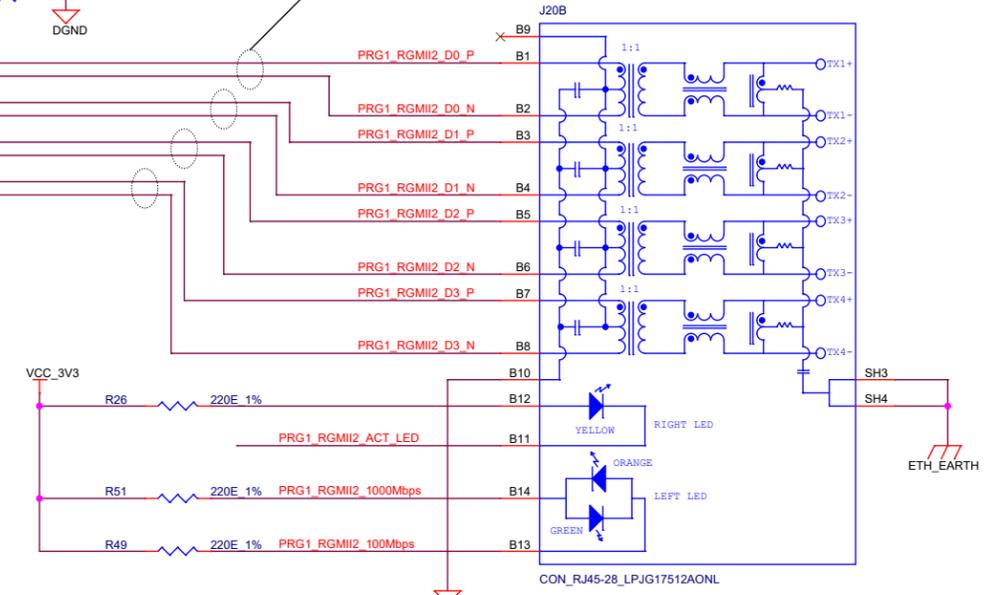


Silk Screen for J20 TOP : "PRG1\_RGMII2"



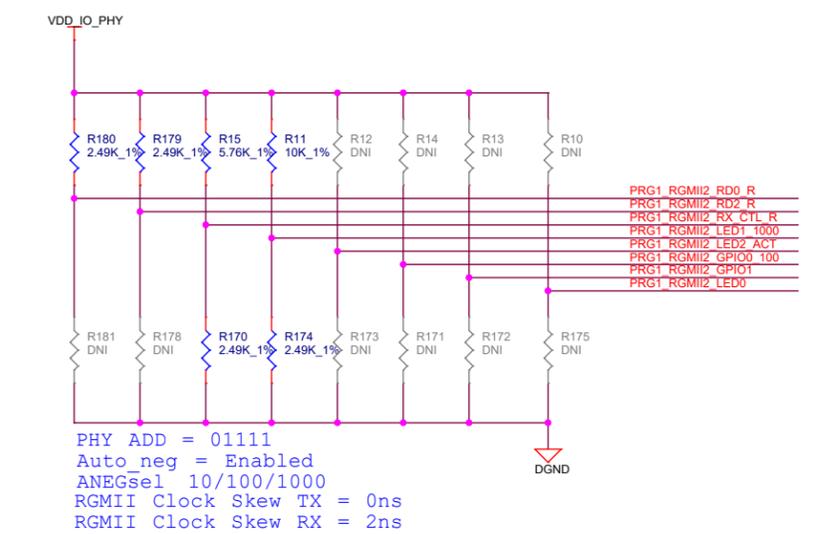
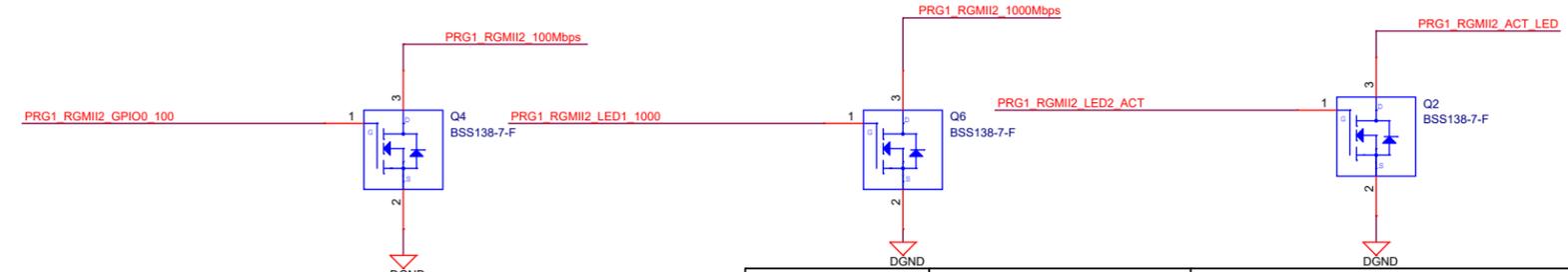
PCB Note: Route signals as 100-ohm differential

## RJ45

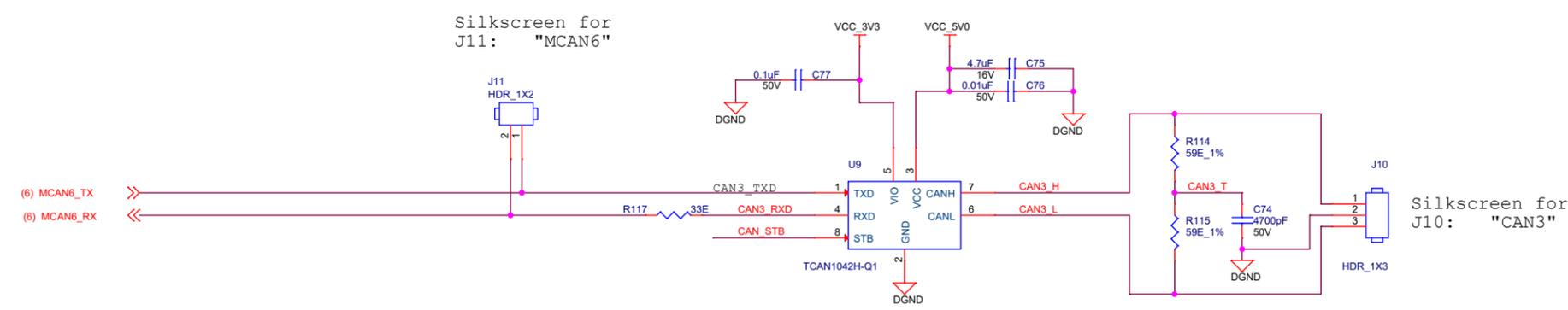
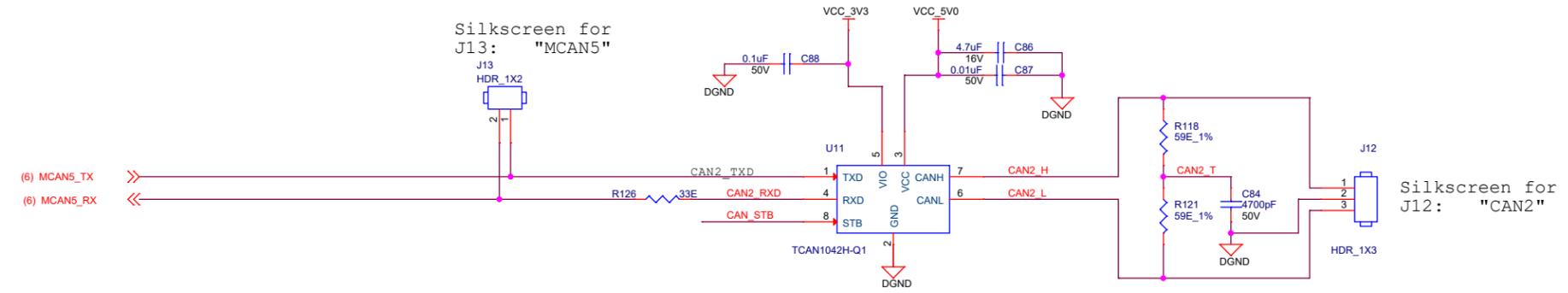
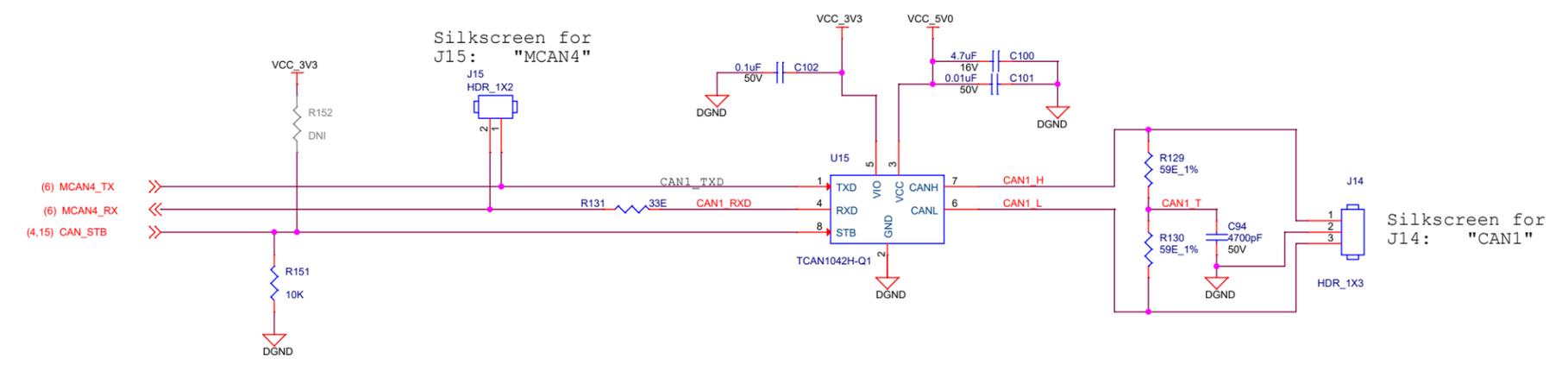


RJ45-LED	FUNCTION
YELLOW	ACTIVITY
ORANGE	1000Mbps Speed
GREEN	100Mbps Speed

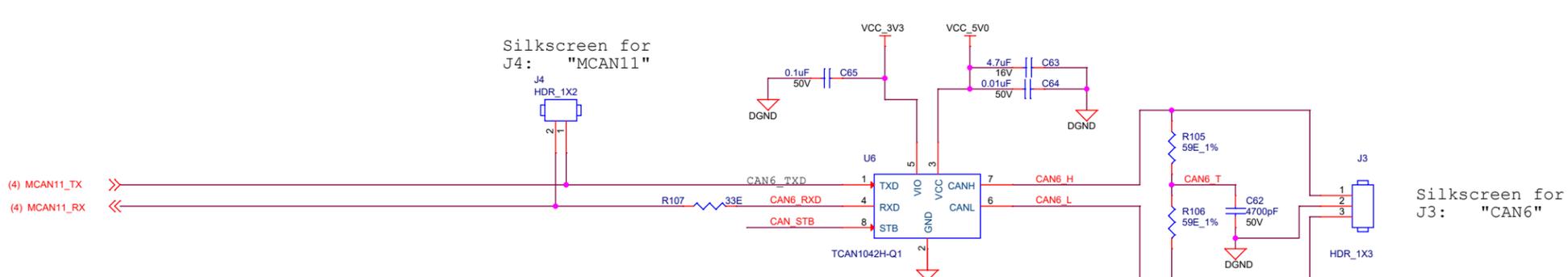
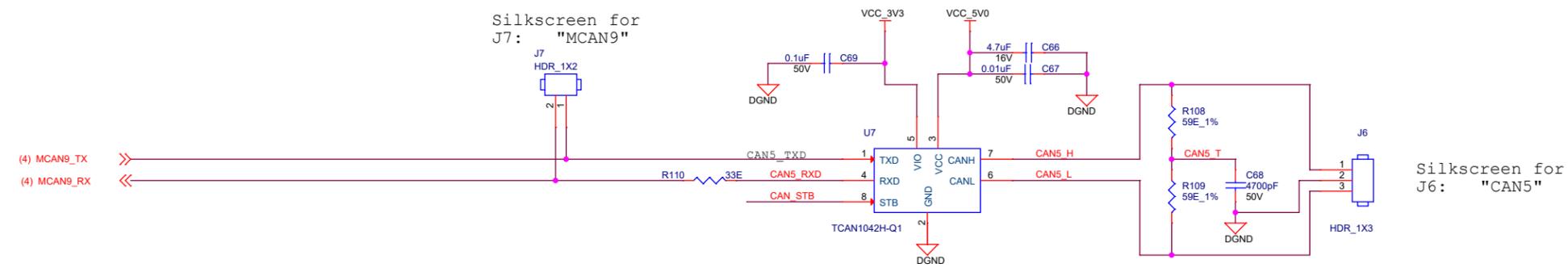
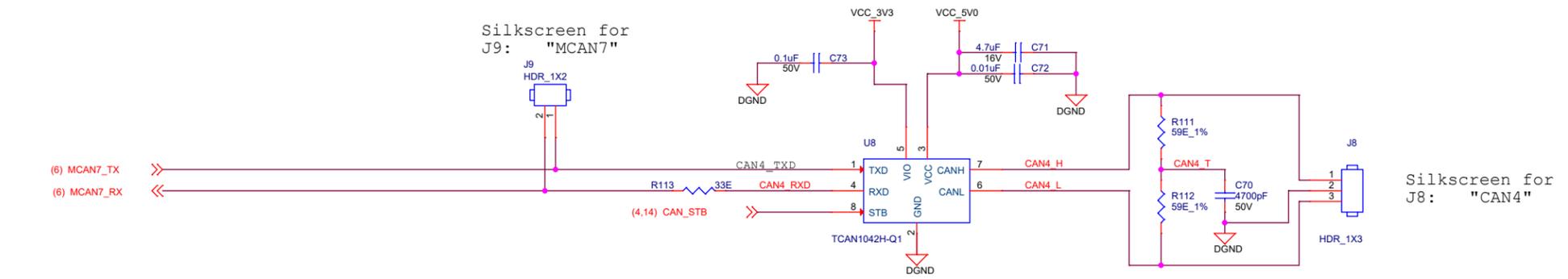
## SPEED AND ACTIVITY LED DRIVERS



# CAN TRANSCEIVERS - 01

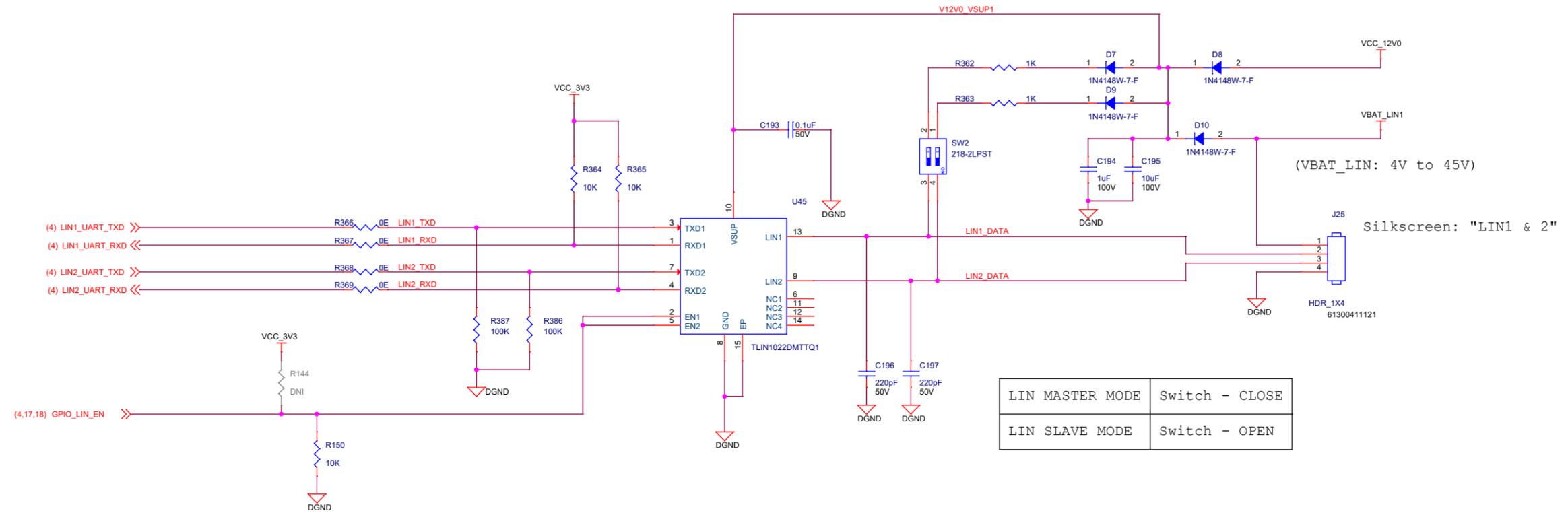


# CAN TRANSCEIVERS - 02

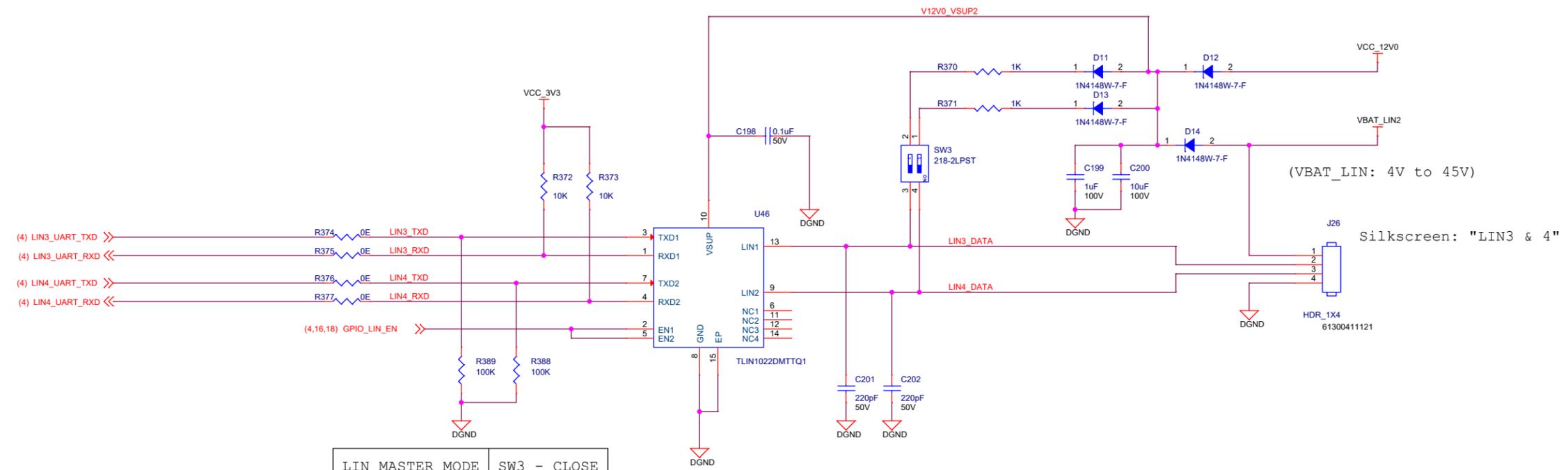


Project : J7 EVM		Title CAN TRANSCEIVERS - 02	
		Size C	PROC084 001 J7EXPC01EVM
		Date: Thursday, December 05, 2019	Rev E3A
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# LIN INTERFACE - 01

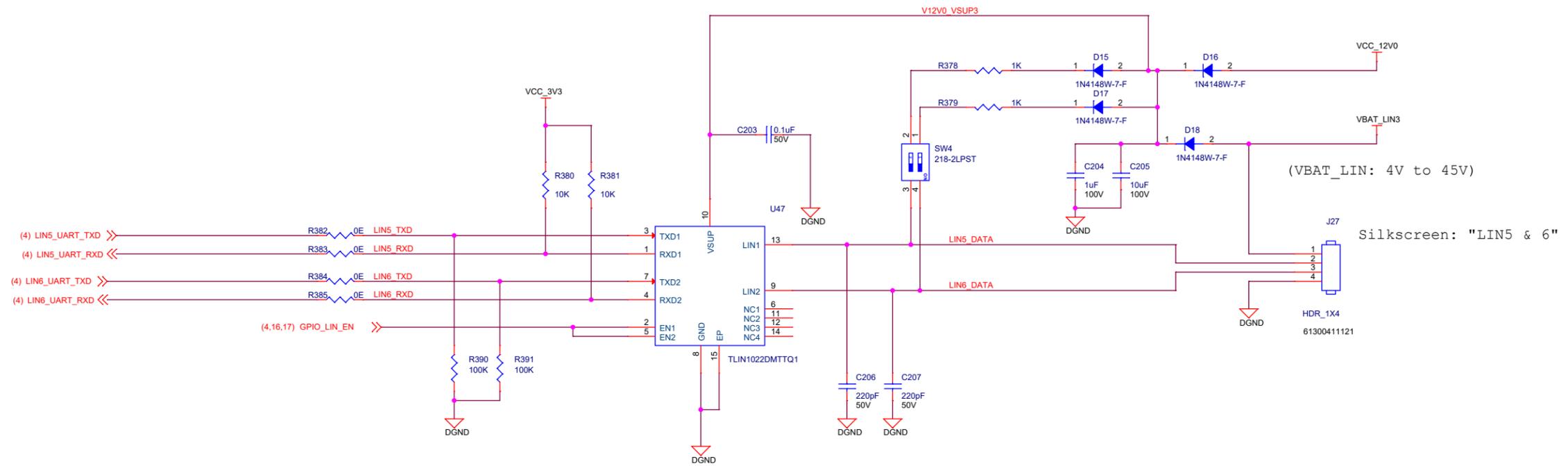


# LIN INTERFACE - 02



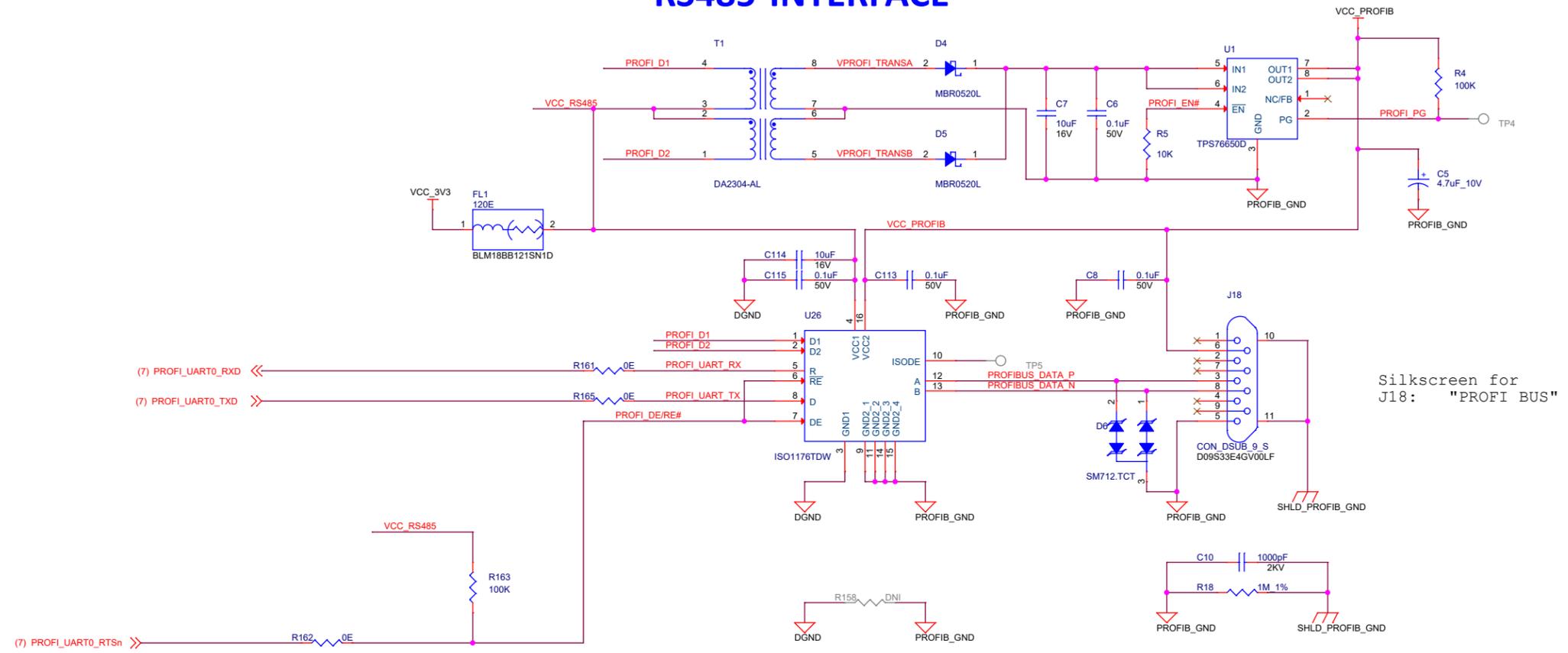
LIN MASTER MODE	SW3 - CLOSE
LIN SLAVE MODE	SW3 - OPEN

# LIN INTERFACE - 03



LIN MASTER MODE	SW4 - CLOSE
LIN SLAVE MODE	SW4 - OPEN

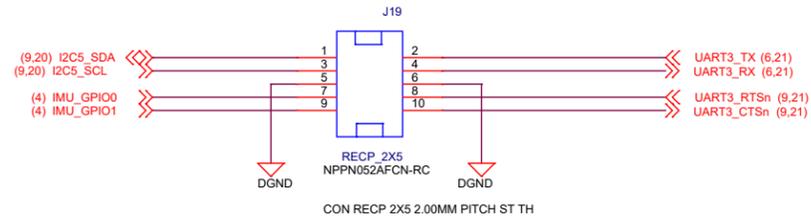
# RS485 INTERFACE



Silkscreen for J18: "PROFI BUS"

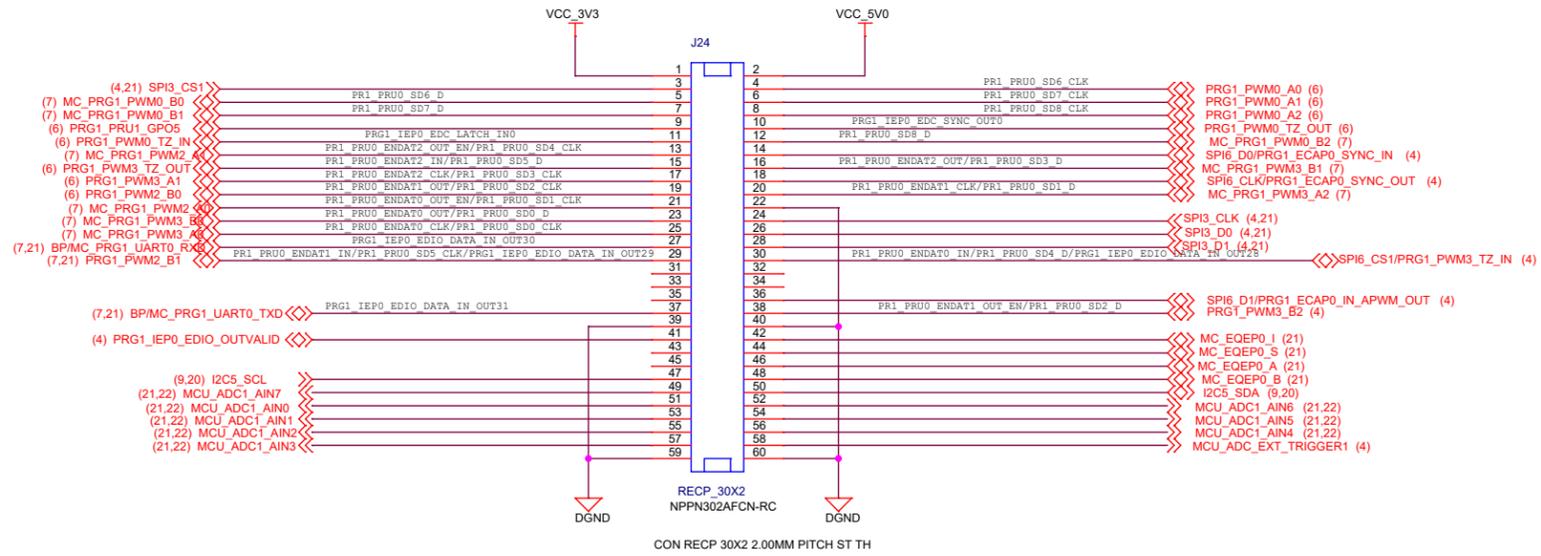
Project : J7 EVM		Title : RS485 INTERFACE	
		Size : PROC084 001 J7EXPC01EVM	Rev : E3A
		Date : Thursday, December 05, 2019	Sheet 19 of 25

# USS/IMU SENSOR HEADER



Silkscreen for J19:  
"IMU/USS HDR"

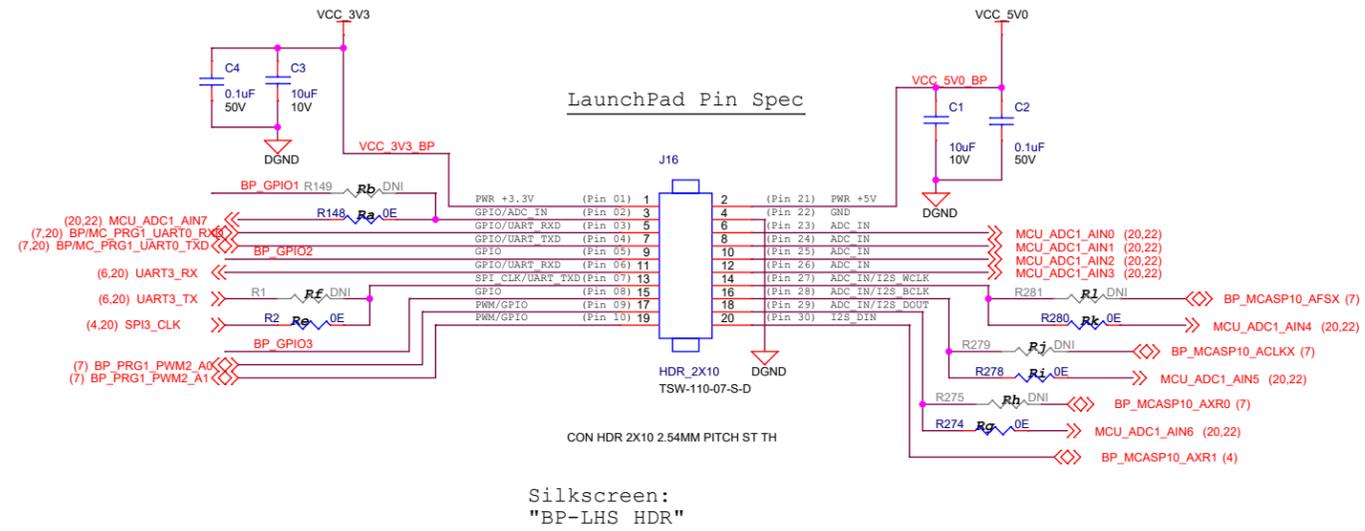
# MOTOR CONTROL HEADER



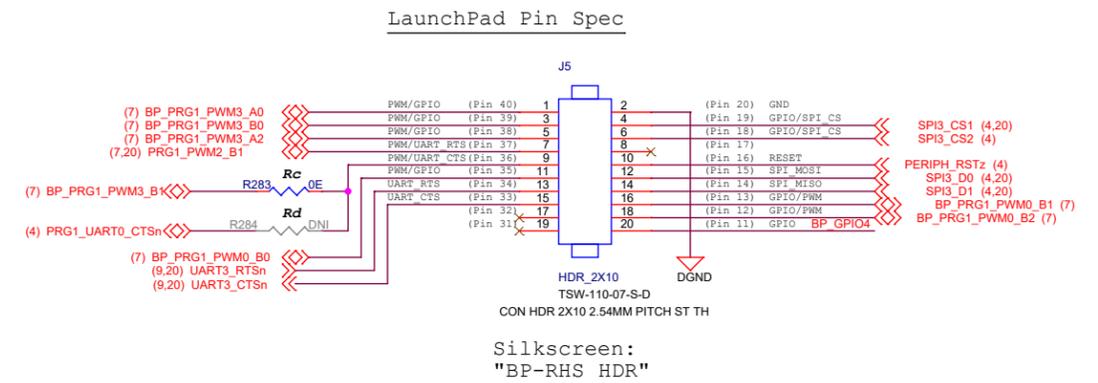
Silkscreen for J24:  
"MOTOR CNTRL HDR"

# GESI LAUNCHPAD- BOOSTERPACK INTERFACE HEADERS

## BOOSTER PACK I/F LHS CONN.

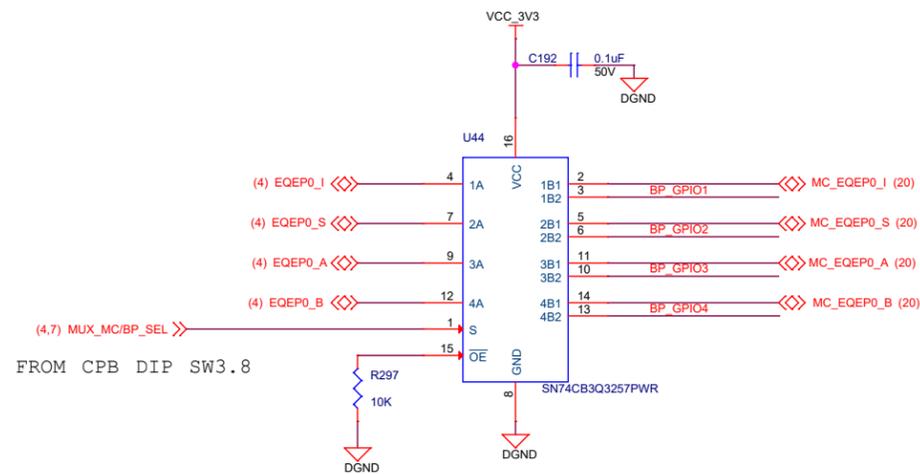


## BOOSTER PACK I/F RHS CONN.

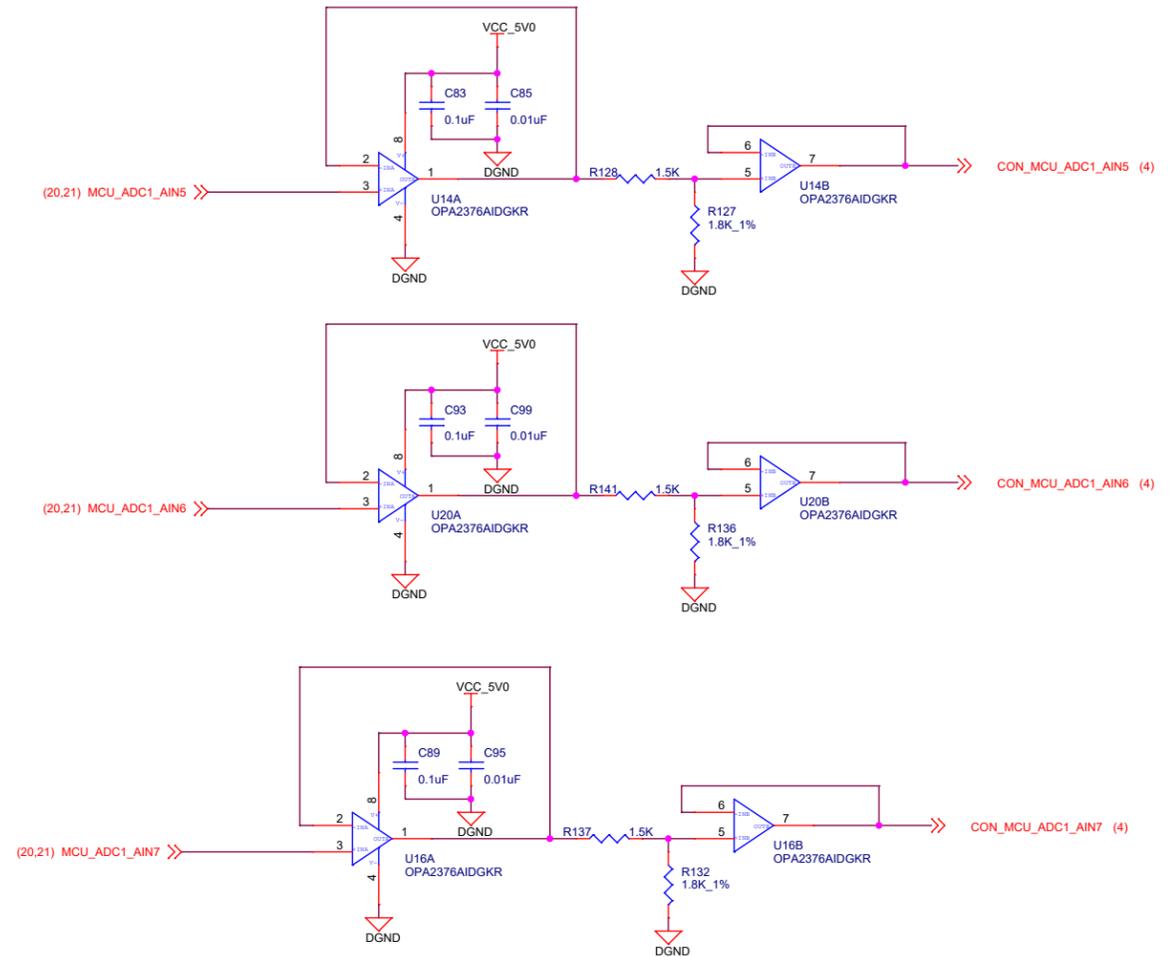
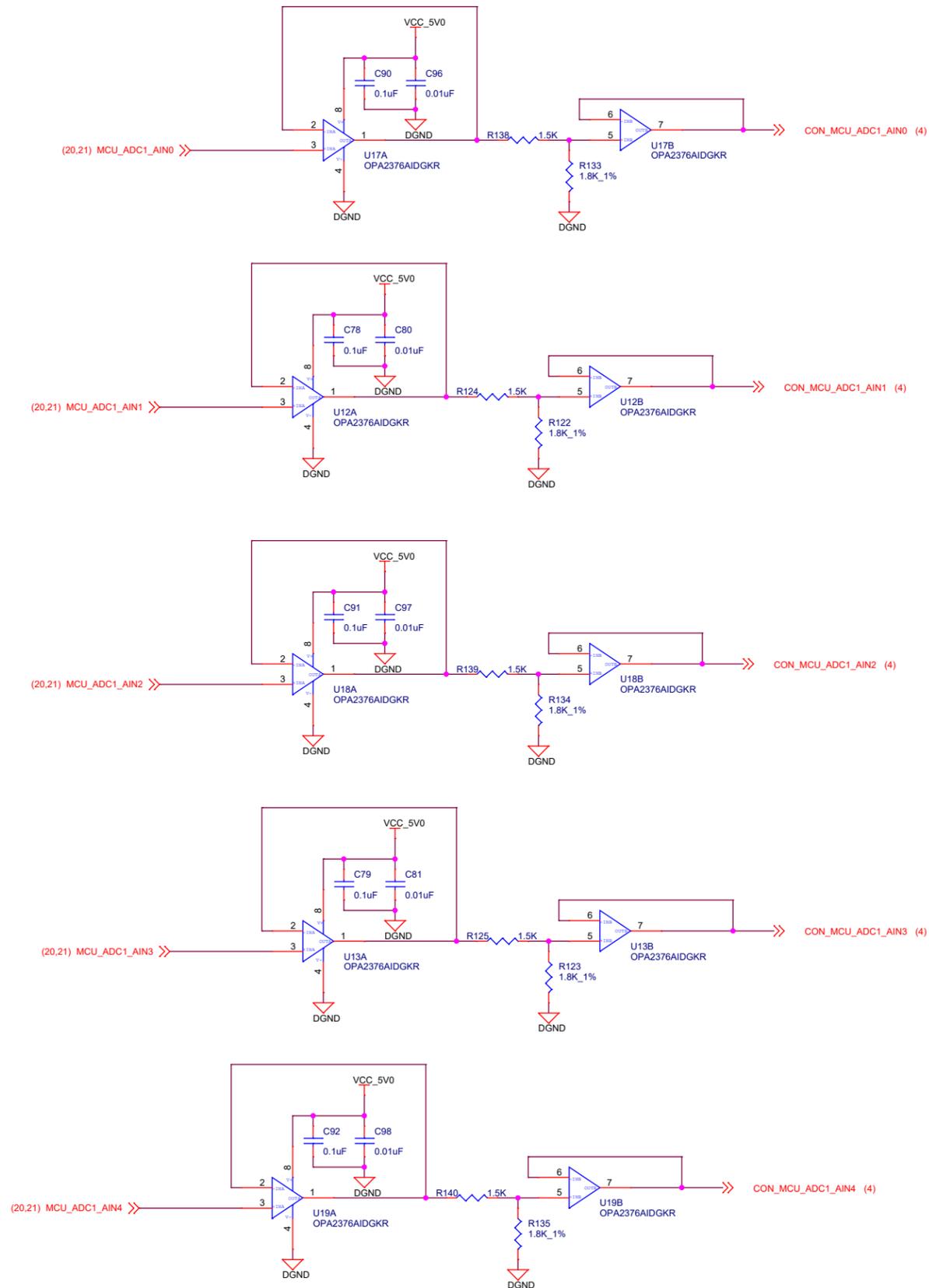


NOTE: Except BOOST-DRV8848 all other below listed BP interfaces supported similar to maxwell EVM

S.No	Supported Booster Packs	Part to be mounted	Part not be mounted
1	BOOSTXL-ULN2003	<b>Ra</b>	<b>Rb</b>
2	BOOST-DRV8711	<b>Rb</b>	<b>Ra</b>
3	BOOSTXL-DRV8301	<b>Rc</b>	<b>Rd</b>
4	CC3100BOOST	<b>Rd</b>	<b>Rc</b>
5	BOOST-CC2564MODA	<b>Rd Rf Rh Rj Rl</b>	<b>Rc Re Rg Ri Rk</b>

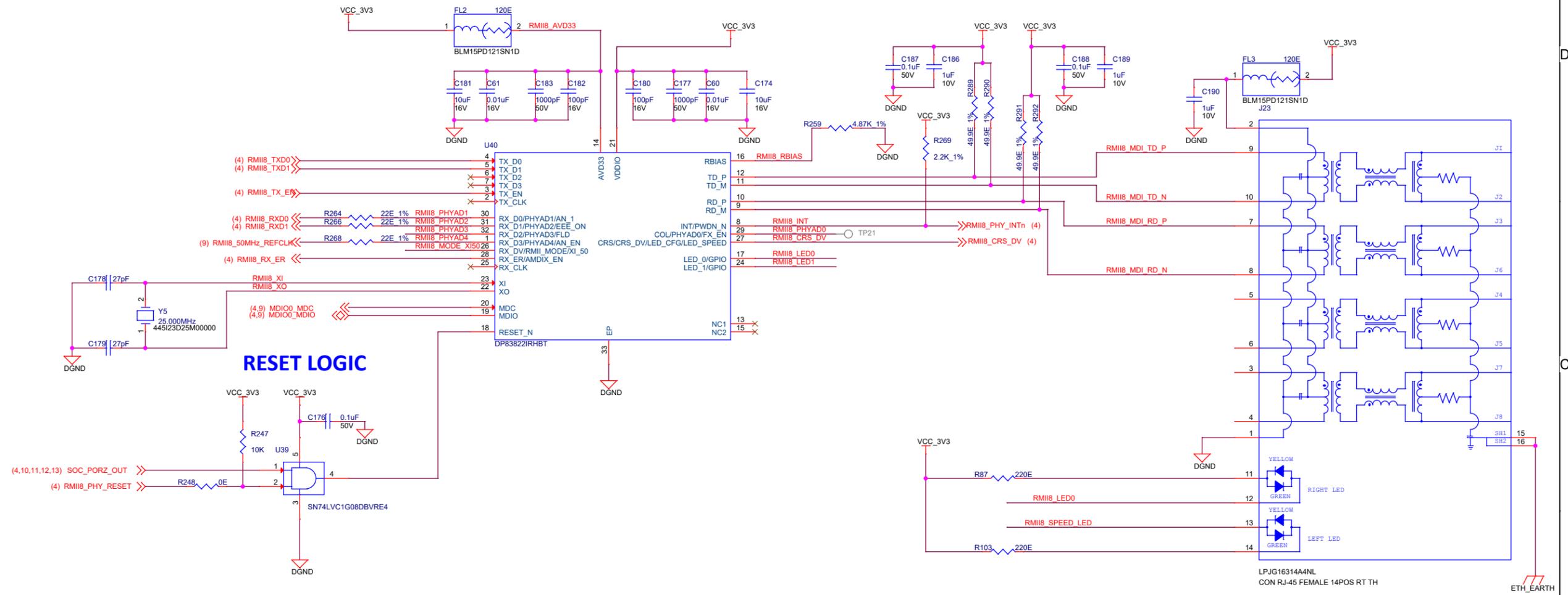


# ADC IN

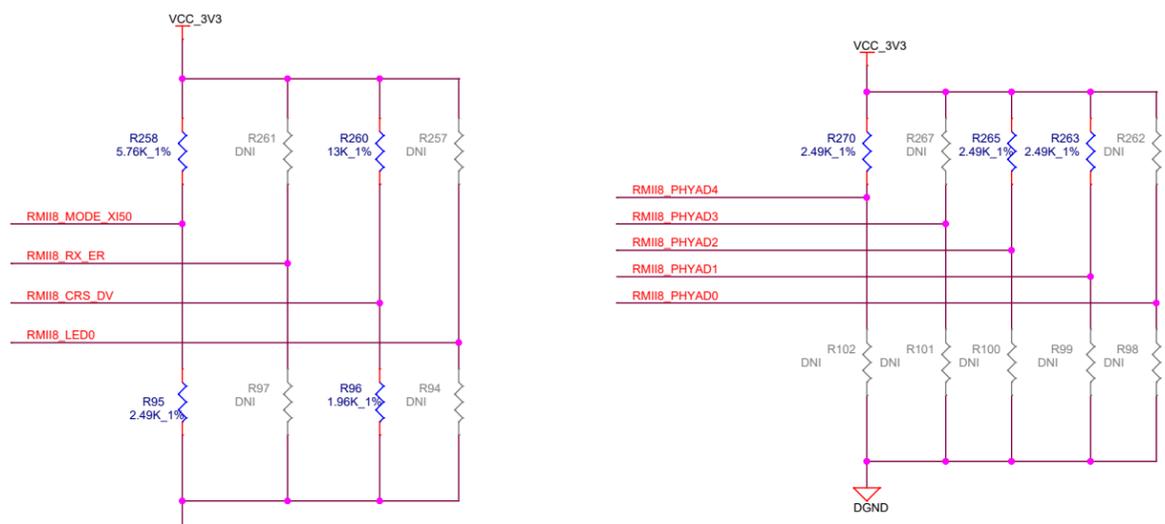


Project :		Title	
J7 EVM		ADC IN	
Size	PROC084 001 J7EXPC01EVM	Rev	
C		E3A	
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# RMI18 INTERFACE



## RESISTOR STRAPPING

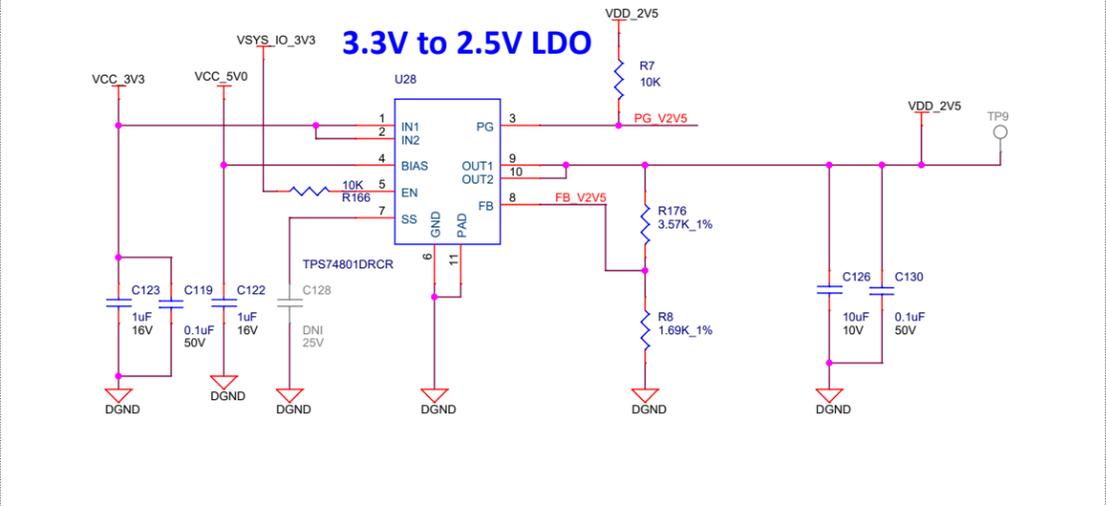


**PHY ADD : 10111**

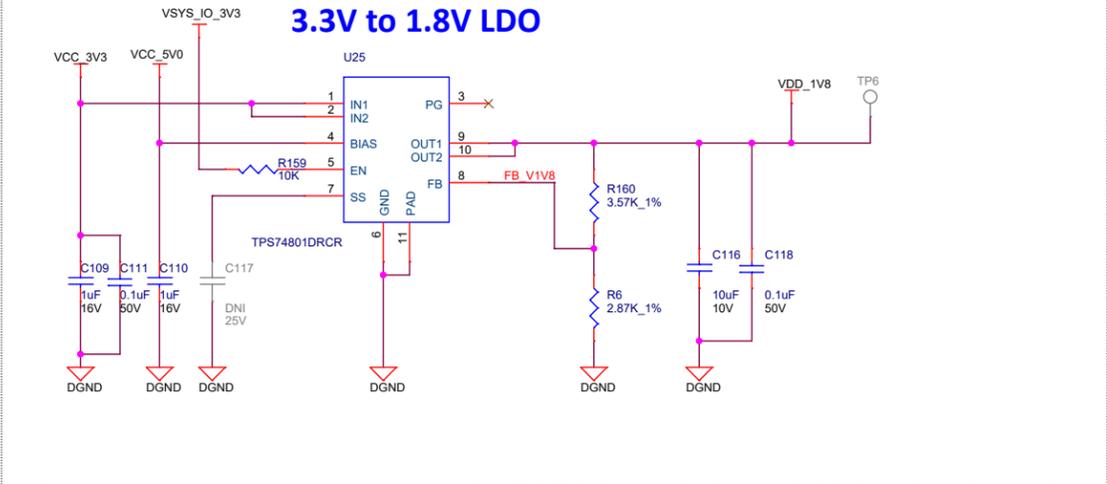
PHY	Address	Value
QSGMII_PHY0	10000	0x10
QSGMII_PHY1	10001	0x11
QSGMII_PHY2	10010	0x12
QSGMII_PHY3	10011	0x13
PRG0_RGMI11	00000	0x00
PRG0_RGMI12	00011	0x03
PRG1_RGMI11	01100	0x0C
PRG1_RGMI12	01111	0x0F
RMI18	10111	0x17

# POWER SUPPLY

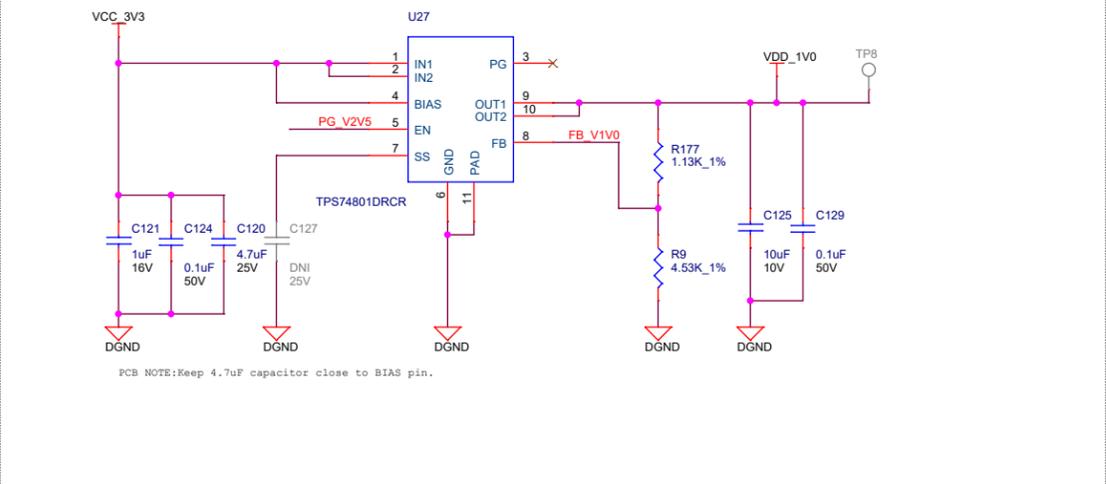
## ETHERNET POWER



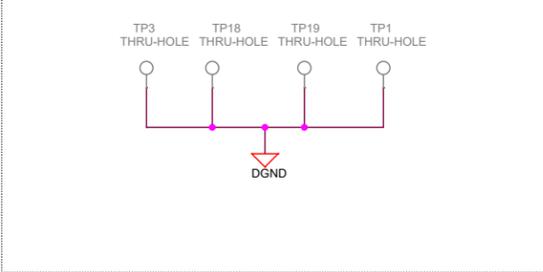
### 3.3V to 1.8V LDO



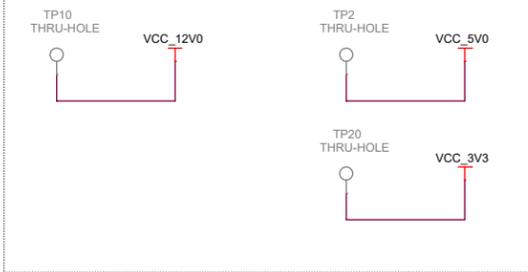
### 3.3V to 1.0V LDO



## GROUND TEST POINTS



## POWER TEST POINTS



# HARDWARE SCHEMATICS

## ASSEMBLY NOTES

1. All MSL components should be baked as per JEDEC standard.
2. PCB should be baked at 120 degree for 8 hours.
3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
4. These assemblies are ESD sensitive, ESD precautions shall be observed.
5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
6. Provide serial numbers to the assembled boards for identification.
7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

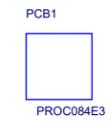
## FIDUCIALS



## WASHERS

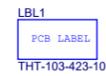


## BARE PCB



## LABELS

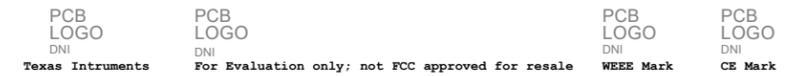
### Board Serial No.



### Assembly Revision.



## LOGOs



Project :

J7 EVM



Title  
HARDWARE SCHEMATICS

Size  
C    PROC084 001 J7EXPC01EVM

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Rev

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